

**HEAT DISSIPATING DEVICE
WITH PRESELECTED DESIGNED INTERFACE
FOR THERMAL INTERFACE MATERIALS**

Abstract

Embodiments of the invention includes a heat dissipating device. The heat dissipating device includes a main body having a surface, wherein the surface is plated or coated with at least two different metals to form a design effective for bonding to solder and for adhering to polymer in a polymer solder hybrid. The heat dissipating device also includes surface perturbations.

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